

TI Heat resistant resin - prepd from polycarbodiimide having terminal

isocyanate gps, used in paints, binders adhesives etc.

DC A25 A82 G02

PA (DNIN) DAINIPPON INK & CHEM KK

CYC 1

PI JP--72033279 B (197235)\* <--

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AN 1972-56313T [35] WPIDS

AB JP 72033279 B UPAB: 19930831

Process comprises reacting a polycarbodiimide contg terminal isocyanates

gps (prepd. by polymerisation of an organic diisocyanate (I), with a cpd.

(II) of gen. formula:- X-A-X, X-A Y or Y A Y (where X is COOH, Y is acid

anhydride gp, A is 2 to 4 valent radical containing  $\geq 1$  ring having

benzenic unsatd bonds) in such a ratio that NCO gp/X or Y gp. is 0.8/1 to

1/0.8 (equivalent/equivalent). The diisocyanate (I) is e.g. MDI,

diphenylether-4,4'-diisocyanate, 3,3'-dimethyl diphenyl-4,4'-diisocyanate,

HMDI, XDI, etc. and (II) is e.g. isophthalic acid, terephthalic acid,

trimellitic acid anhydride, pyromellitic acid dianhydride, benzophenone

tetracarboxylic acid, terephthalic acid, trimellitic acid anhydride,

pyromellitic acid dianhydride, benzophenone tetracarboxylic acid

dianhydride, etc. Reaction is carried out at 50 degrees to 160 degrees C

in the presence of an inert solvent and an inert gas.